

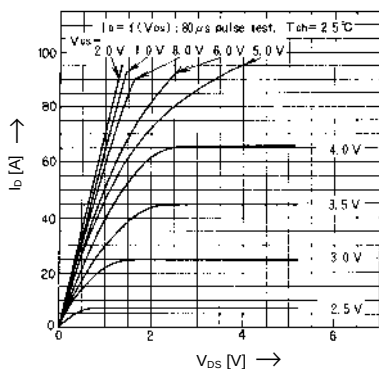
| Item               | Symbol         | Test conditions | Min. | Typ. | Max. | Unit |
|--------------------|----------------|-----------------|------|------|------|------|
| Thermal Resistance | $R_{th(ch-a)}$ | channel to air  |      |      | 75   | °C/W |
|                    | $R_{th(ch-c)}$ | channel to case |      |      | 1.56 | °C/W |

# 2SK2049

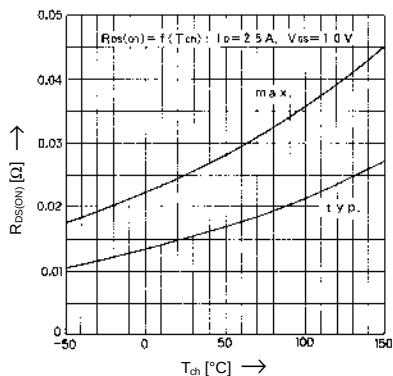
## F-III Series

### > Characteristics

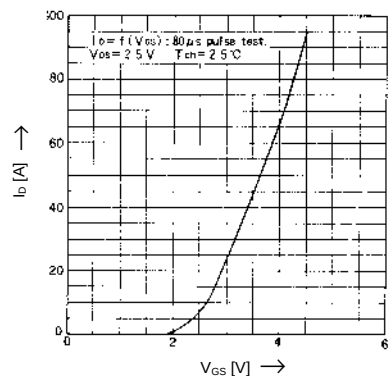
Typical Output Characteristics



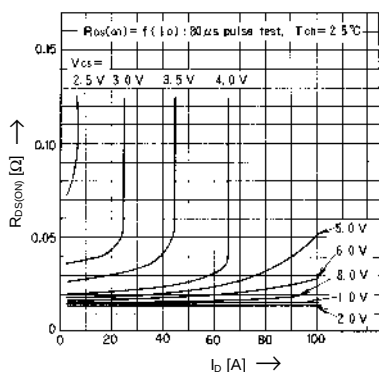
Drain-Source-On-State Resistance vs.  $T_{ch}$



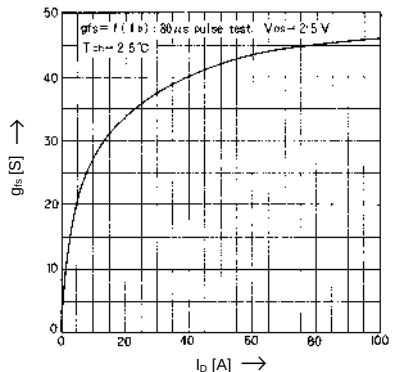
Typical Transfer Characteristics



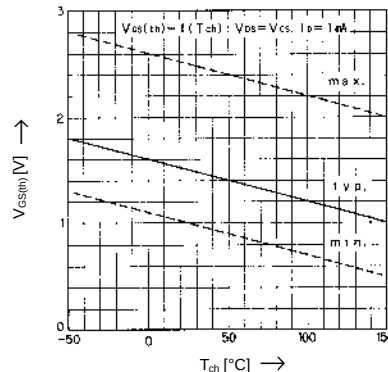
Typical Drain-Source-On-State-Resistance vs.  $I_D$



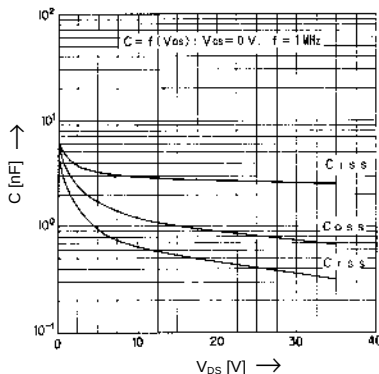
Typical Forward Transconductance vs.  $I_D$



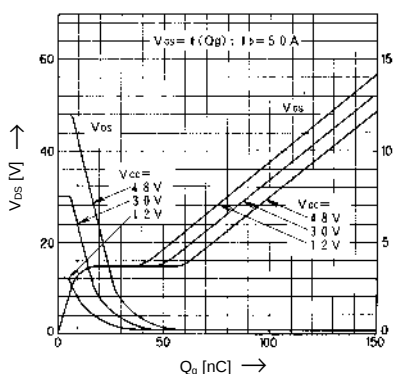
Gate Threshold Voltage vs.  $T_{ch}$



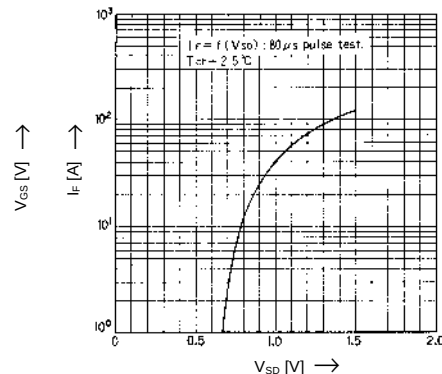
Typical Capacitance vs.  $V_{DS}$



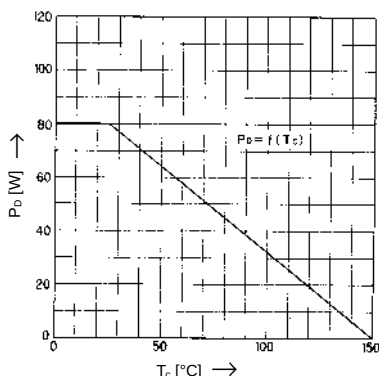
Typical Input Charge



Forward Characteristics of Reverse Diode



Allowable Power Dissipation vs.  $T_c$



Safe operation area

